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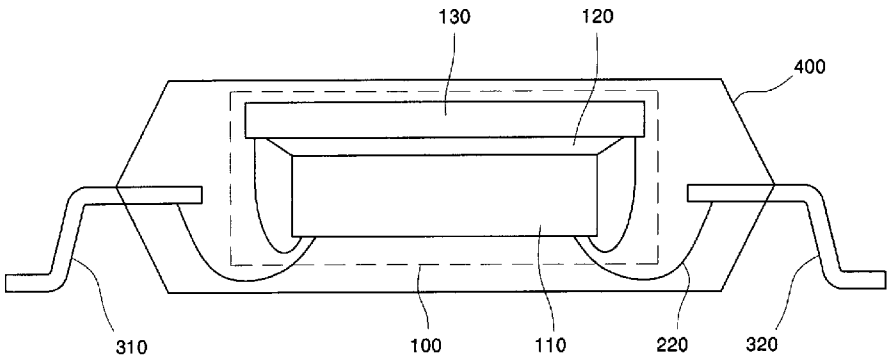
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(54) **Title:** SEMICONDUCTOR DEVICE AND TOUCH SENSOR DEVICE



(57) **Abstract:** Provided are a semiconductor device and a touch sensor device. The semiconductor device includes a die including a sense signal generator for sensing a touch signal to generate a sense signal; a conductive die-attach pad attached to the die to generate the touch signal; and a package for packaging the die and the die-attach pad, wherein the die-attach pad generates the touch signal depending on whether a touch object comes into contact with the package. The touch sensor device includes a plurality of semiconductor devices connected in a daisy-chain communication mode, wherein each of the semiconductor devices includes a die including a sense signal generator for sensing a touch signal to generate a sense signal; a conductive die-attach pad attached to the die to generate the touch signal; and a package for packaging the die and the die-attach pad, wherein the die-attach pad generates the touch signal depending on whether a touch object is brought into contact with the package. The semiconductor device enables the size and position of a touch pad to be known in advance during the fabrication of a die so that a sensitivity adjusting process can be simplified. Also, since the touch pad is included in a touch sensor, a system can be simply configured at low cost. Furthermore, the touch sensor device requires no additional sensitivity adjusting process and enables a plurality of touch sensor systems to be constructed at low cost by simply connecting a small number of electrical signals.

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